

MECHANICAL CASE OUTLINE

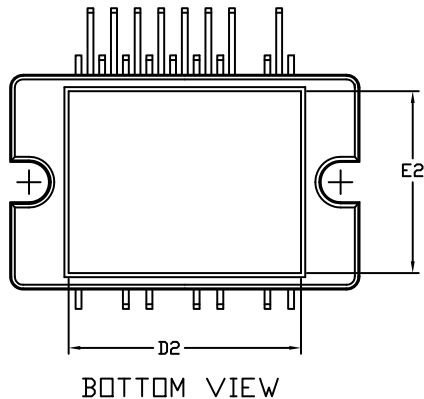
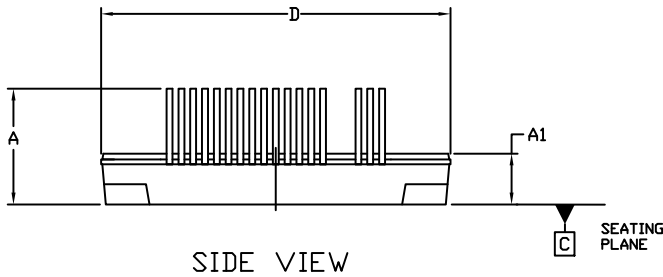
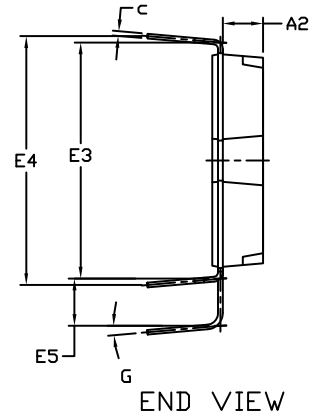
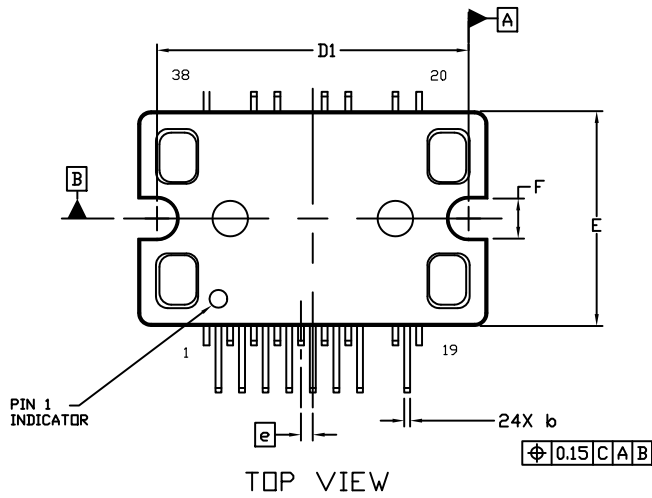
PACKAGE DIMENSIONS

ON Semiconductor®



MODULE SPCM24 29.6x18.2 DIP S3 CASE MODBL ISSUE A

DATE 08 MAR 2016



NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 2009.
2. CONTROLLING DIMENSION: MILLIMETERS
3. DIMENSION *b* APPLIES TO THE PLATED LEAD AND IS MEASURED BETWEEN 0.10 AND 0.25 FROM THE LEAD TIP.
4. PACKAGE IS MISSING PINS: 15, 16, 21, 23, 24, 25, 27, 29, 30, 31, 33, 35, 36, AND 37.

DIM	MILLIMETERS	
	MIN.	MAX.
A	9.30	10.30
A1	3.80	4.80
A2	2.90	3.90
<i>b</i>	0.45	0.70
<i>c</i>	0.35	0.60
D	29.10	30.10
D1	26.30	26.50
D2	19.20	20.20
E	17.70	18.70
E2	14.90	15.90
E3	19.50	20.50
E4	21.10 REF	
E5	3.50	4.50
<i>e</i>	1.00 BSC	
F	2.90	3.90
G	4°	6°

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